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### **AIM to Participate at IPC APEX EXPO on February 4-6, 2020**

**December 20<sup>th</sup>, 2019 — Cranston, Rhode Island USA** — AIM Solder, a leading global manufacturer of solder assembly materials for the electronics industry, is pleased to announce their upcoming attendance at IPC APEX EXPO 2020 taking place February 4-6, 2020 at the San Diego Convention Center in San Diego, California. AIM will highlight their [NC273LT](#) low temperature solder paste for bismuth bearing alloys, RX18 and CX18 no clean flux cored solder wire along with their full line of solder assembly materials.



AIM's NC273LT low temperature solder paste provides assemblers another tool to meet the changing needs of an evolving PCB assembly market. With peak reflow temperatures below 170°C, NC273LT reduces component and substrate warpage, reduces thermal exposure and saves energy. NC273LT paste improves the wetting performance of bismuth alloys to RoHS compliant plating and surface finishes. NC273LT provides long stencil life, excellent transfer efficiencies and minimizes solder balling common to high bismuth alloys. When thermal exposure during the assembly process is a limitation, NC273LT is an excellent RoHS compliant replacement.

AIM's [RX18](#) and [CX18](#) continue to achieve unprecedented customer acceptance. Engineered for automated/robotic selective soldering, RX18 promotes thermal transfer, fast wetting and reduces voids/skips. Additionally, RX18 extends solder iron tip life and leaves minimal flux residue. CX18 is an operator friendly, low odor/smoke formula, and speeds soldering performance leaving a clear, electrically safe residue that does not require removal. Further throughput and reliability gains can be realized when CX18 and RX18 are combined with AIM's REL61™ and REL22™ alloys. [REL22](#) improves product survival in extreme thermal exposure operating environments such as under-hood automotive, avionics/aerospace and LED lighting. [REL61](#) is ideally suited for industries which require a cost effective alternative to SAC305 with no loss of processing performance or durability.

Along with these products, AIM will also showcase its full line of advanced solder materials, including solder paste, liquid flux and solder alloys. Visit AIM at IPC APEX EXPO 2020 in Booth # 2447 at the San Diego Convention Center, San Diego, CA for more information and to speak with one of AIM's knowledgeable staff members.

#### **About AIM**

Headquartered in Montreal, Canada, AIM Solder is a leading global manufacturer of assembly materials for the electronics industry with manufacturing, distribution and support facilities located throughout the world. AIM produces advanced solder products such as solder paste, liquid flux, cored wire, bar solder, epoxies, lead-free and halogen-free solder products, and specialty alloys such as indium and gold for a broad range of industries. A recipient of many prestigious SMT industry awards, AIM is strongly committed to innovative research and development of product and process improvement as well as providing customers with superior technical support, service and training. For more information about AIM, visit [www.aimsolder.com](http://www.aimsolder.com).